

Laminated board for printed circuit, having high tracking resistance - has surface layer of woven glass fibre prep'd by impregnating polyepoxy resin compsn and nonwoven glass fibre core layer.

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Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 6302926	A	19941028	JP 9385995	A	19930413	199503 B
JP 2787846	B2	19980820	JP 9385995	A	19930413	199838

Priority Applications (No Type Date): JP 9385995 A 19930413

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 6302926	A	4	H05K-001/03	
JP 2787846	B2	3	H05K-001/03	Previous Publ. patent JP 6302926

Abstract (Basic): JP 6302926 A

Laminated board has surface layer(s) of woven glass fibre prep'd by impregnating an epoxy resin compsn comprising 100 pts wt epoxy resin free from Br, 10-200 pts wt inorganic filler and nonwoven glass fibre core layer(s) prep'd by impregnating a resin compsn comprising 100 pts wt brominated epoxy resin and 10-200 pts wt inorganic filler.

The inorganic filler is pref hydrated Al2O3 which is decomposed by discharge heat to form volatile prods and to prevent the tracking. The epoxy varnish for the surface layer comprises eg 100 pts wt epoxy resin free from Br, 4 pts wt dicyandiamide, 2 pts wt 2-phenyl-4-methylimidazole, 20 pts wt methylcellosolve, 30 pts wt acetone and 50 pts wt Al hydroxide of gypsum type. The epoxy varnish for the core layer comprises 100 pts wt brominated epoxy resin, 4 pts wt dicyandiamide, 0.15 pts wt 2-ethyl-4-methylimidazole, 36 pts wt methylcellosolve, 60 pts wt acetone and 60 pts wt Al hydroxide of gypsum type.

ADVANTAGE - The laminated board has high tracking resistance, flame-resistance and peeling strength of Cu foil.

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Title Terms: LAMINATE; BOARD; PRINT; CIRCUIT; HIGH; TRACK; RESISTANCE; SURFACE; LAYER; WOVEN; GLASS; FIBRE; PREPARATION; IMPREGNATE; POLYEPOXIDE ; RESIN; COMPOSITION; NONWOVEN; GLASS; FIBRE; CORE; LAYER

Derwent Class: A21; A85; L03; P73; V04

International Patent Class (Main): H05K-001/03

International Patent Class (Additional): B32B-005/28; B32B-027/42;

C08J-005/24

File Segment: CPI; EPI; EngPI